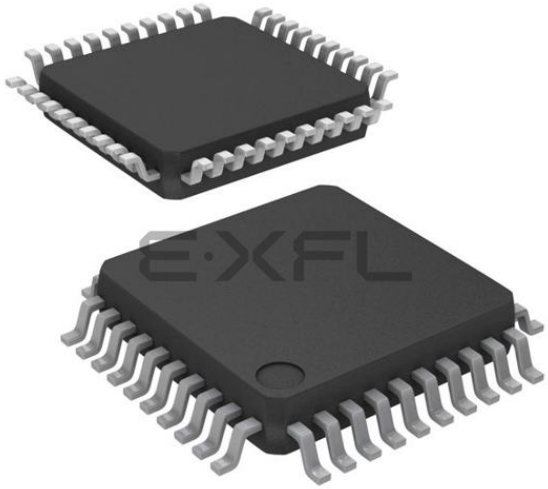
Renesas Electronics America Inc - R7FS128783A01CFJ#AA0 Datasheet



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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	ARM® Cortex®-M0+
Core Size	32-Bit Single-Core
Speed	32MHz
Connectivity	CANbus, DALI, I²C, SCI, SPI, UART/USART, USB
Peripherals	DMA, LVD, POR, PWM, WDT
Number of I/O	24
Program Memory Size	256KB (256K x 8)
Program Memory Type	FLASH
EEPROM Size	4K x 8
RAM Size	24K x 8
Voltage - Supply (Vcc/Vdd)	1.6V ~ 5.5V
Data Converters	A/D 10x14b; D/A 3x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	32-LQFP
Supplier Device Package	32-LQFP (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r7fs128783a01cfj-aa0

Table 1.3 System (2 of 2)

Feature	Functional description
Resets	13 types of resets: • RES pin reset • Power-on reset • Independent watchdog timer reset • Watchdog timer reset • Voltage monitor 0 reset • Voltage monitor 1 reset • Voltage monitor 2 reset • SRAM parity error reset • SRAM ECC error reset • Bus master MPU error reset • Bus slave MPU error reset • CPU stack pointer error reset • Software reset. See section 5, Resets in User's Manual.
Low Voltage Detection (LVD)	The Low Voltage Detection (LVD) monitors the voltage level input to the VCC pin, and the detection level can be selected using a software program. See section 7, Low Voltage Detection (LVD) in User's Manual.
Clock	• Main clock oscillator (MOSC) • Sub-clock oscillator (SOSC) • High-speed on-chip oscillator (HOCO) • Middle-speed on-chip oscillator (MOCO) • Low-speed on-chip oscillator (LOCO) • Independent watchdog timer on-chip oscillator • Clock out support. See section 8, Clock Generation Circuit in User's Manual.
Clock Frequency Accuracy Measurement Circuit (CAC)	The Clock Frequency Accuracy measurement circuit (CAC) checks the system clock frequency with a reference clock signal by counting the number of pulses of the system clock to be measured. The reference clock can be provided externally through a CACREF pin or internally from various on-chip oscillators. Event signals can be generated when the clock does not match or measurement ends. This feature is particularly useful in implementing a fail-safe mechanism for home and industrial automation applications. See section 9, Clock Frequency Accuracy Measurement Circuit (CAC) in User's Manual.
Interrupt Controller Unit (ICU)	The Interrupt Controller Unit (ICU) controls which event signals are linked to the NVIC/DTC module. The ICU also controls NMI interrupts. See section 12, Interrupt Controller Unit (ICU) in User's Manual.
Key interrupt function (KINT)	A key interrupt can be generated by setting the Key Return Mode register (KRM) and inputting a rising or falling edge to the key interrupt input pins. See section 18, Key Interrupt Function (KINT) in User's Manual.
Low Power Mode	Power consumption can be reduced in multiple ways, including setting clock dividers, stopping modules, selecting power control mode in normal operation, and transitioning to low power modes. See section 10, Low Power Modes in User's Manual.
Register Write Protection	The register write protection function protects important registers from being overwritten due to software errors. See section 11, Register Write Protection in User's Manual.
Memory Protection Unit (MPU)	Four MPUs and a CPU stack pointer monitor function are provided for memory protection. See section 14, Memory Protection Unit (MPU) in User's Manual.
Watchdog Timer (WDT)	The Watchdog Timer (WDT) is a 14-bit down-counter. It can be used to reset the MCU when the counter underflows because the system has run out of control and is unable to refresh the WDT. In addition, a non-maskable interrupt or interrupt can be generated by an underflow. The refresh-permitted period can be set to refresh the counter and used as the condition for detecting when the system runs out of control. See section 24, Watchdog Timer (WDT) in User's Manual.
Independent Watchdog Timer (IWDT)	The Independent Watchdog Timer (IWDT) consists of a 14-bit down-counter that must be serviced periodically to prevent counter underflow. The IWDT provides functionality to reset the MCU or to generate a non-maskable interrupt/interrupt for a timer underflow. Because the timer operates with an independent, dedicated clock source, it is particularly useful in returning the MCU to a known state as a fail safe mechanism when the system runs out of control. The IWDT can be triggered automatically on a reset, underflow, refresh error, or by a refresh of the count value in the registers. See section 25, Independent Watchdog Timer (IWDT) in User's Manual.

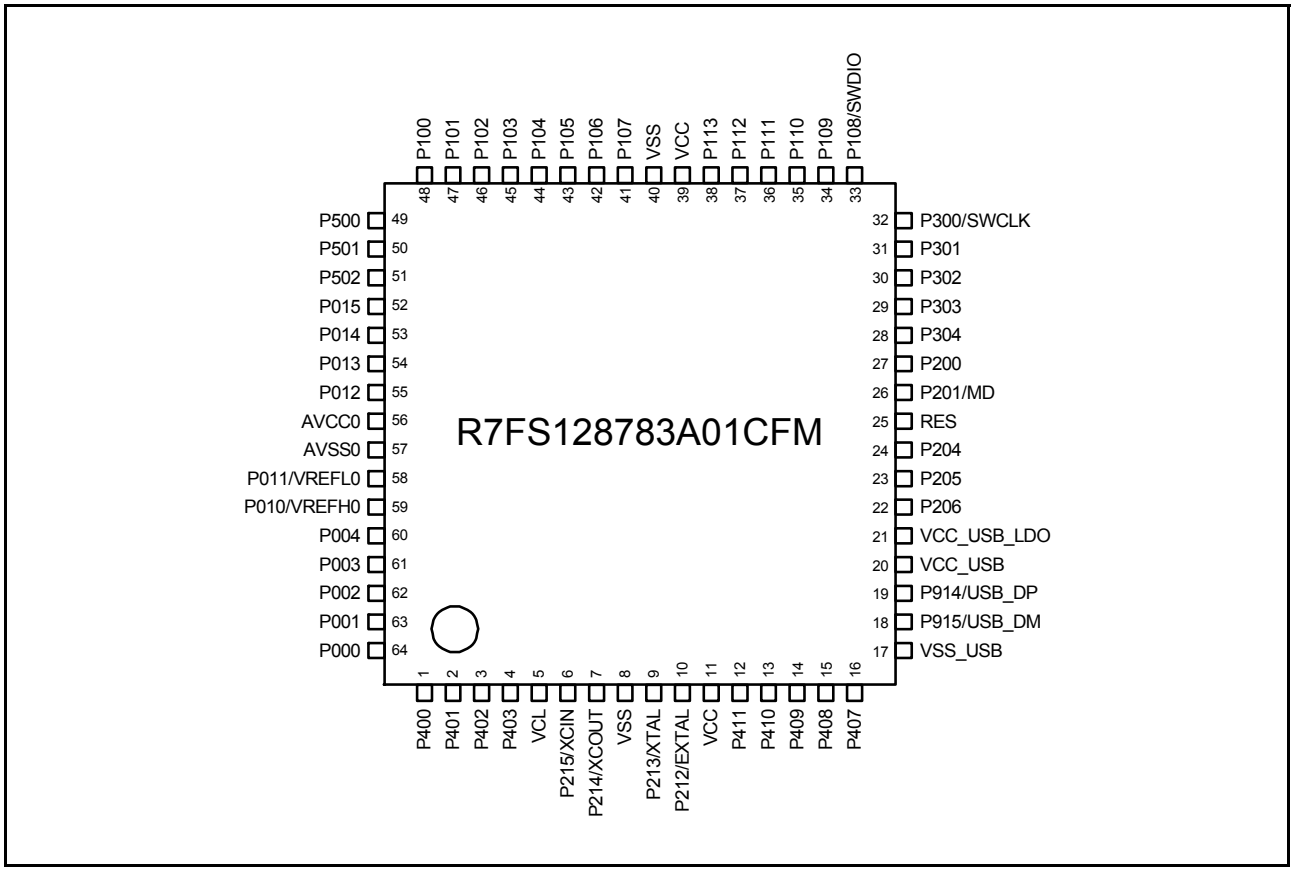


Figure 1.3 Pin assignment for LQFP 64-pin

Pin number						Power, System, Clock, Debug, CAC	I/O ports	Timers				Communication Interfaces				Analogs				HMI	
LQFP64	LQFP48	QFN48	LGA36	LQFP32	QFN32			AGT	GPT_OPS, POEG	GPT	RTC	USBFS,CAN, DALI	SCI	IIC	SPI	ADC14	DAC8	ACMPHS, ACMPLP	OPAMP	CTSU	Interrupt
18	14	14	F2	9	9		P915					USB_DM									
19	15	15	F3	10	10		P914					USB_DP									
20	16	16	F4	11	11	VCC_USB															
21	17	17	F5	12	12	VCC_USB_LDO															
22	18	18	-	-	-		P206		GTIU_A				RXD0_D/ MISO0_D/ SCL0_D	SDA1_A	SSLB1_A					TS01	IRQ0
23	-	-	-	-	-	CLKOUT_A	P205	AGTO1	GTIV_A	GTIOC4A_B			TXD0_D/ MOSI0_D/ SDA0_D/ CTS9_RTS9_A/SS9_A	SCL1_A	SSLB0_A					TSCAP_A	IRQ1
24	-	-	-	-	-	CACREF_A	P204	AGTIO1_A	GTIW_A	GTIOC4B_B			SCK0_D/ SCK9_A	SCL0_B	RSPCKB_A					TS00	
25	19	19	E3	13	13	RES															
26	20	20	E4	14	14	MD	P201														
27	21	21	E5	15	15		P200														NMI
28	-	-	-	-	-		P304			GTIOC1A_B											
29	-	-	-	-	-		P303			GTIOC1B_B										TS02	
30	22	22	-	-	-		P302		GTOUUP_A	GTIOC4A_A					SSLB3_B					TS08	IRQ5
31	23	23	-	-	-		P301	AGTIO0_D	GTOULO_A	GTIOC4B_A			CTS9_RTS9_D/ SS9_D		SSLB2_B					TS09	IRQ6
32	24	24	F6	16	16	SWCLK	P300		GTOUUP_C	GTIOC0A_A					SSLB1_B						
33	25	25	E6	17	17	SWDIO	P108		GTOULO_C	GTIOC0B_A			CTS9_RTS9_B/SS9_B		SSLB0_B						
34	26	26	D4	18	18	CLKOUT_B	P109		GTOVUP_A	GTIOC1A_A		CTX0_A	SCK1_E/ TXD9_B/ MOSI9_B/ SDA9_B		MOSIB_B					TS10	
35	27	27	D5	19	19		P110		GTOVLO_A	GTIOC1B_A		CRX0_A	CTS0_RTS0_C/ SS0_C/ RXD9_B/ MISO9_B/ SCL9_B		MISOB_B			VCOUT		TS11	IRQ3
36	28	28	D6	-	-		P111	AGTOA0		GTIOC3A_A			SCK0_C/ SCK9_B		RSPCKB_B					TS12	IRQ4
37	29	29	C6	20	20		P112	AGTOB0		GTIOC3B_A			TXD0_C/ MOSI0_C/ SDA0_C/ SCK1_D		SSLB0_C					TSCAP_C	
38	-	-	-	-	-		P113			GTIOC2A_C											
39	30	30	-	-	-	VCC															
40	31	31	-	-	-	VSS															
41	-	-	-	-	-		P107			GTIOC0A_B											KR07
42	-	-	-	-	-		P106			GTIOC0B_B					SSLA3_A	AN016					KR06
43	-	-	-	-	-		P105		GTETRGA_C	GTIOC1A_C					SSLA2_A	AN017					KR05/ IRQ0
44	32	32	-	-	-		P104		GTETRGB_B	GTIOC1B_C			RXD0_C/ MISO0_C/ SCL0_C		SSLA1_A	AN018				TS13	KR04/ IRQ1
45	33	33	C3	21	21		P103		GTOWUP_A	GTIOC2A_A		CTX0_C	CTS0_RTS0_A/SS0_A		SSLA0_A	AN019		CMPREF1		TS14	KR03
46	34	34	C4	22	22		P102	AGTO0	GTOWLO_A	GTIOC2B_A		CRX0_C	SCK0_A		RSPCKA_A	AN020/ ADTRG0_A		CMPIN1		TS15	KR02
47	35	35	C5	23	23		P101	AGTEE0	GTETRGB_A	GTIOC5A_A		DTX0	TXD0_A/ MOSI0_A/ SDA0_A/ CTS1_RTS1_A/SS1_A	SDA1_B	MOSIA_A	AN021		CMPREF0		TS16	KR01/ IRQ1
48	36	36	B6	24	24		P100	AGTIO0_A	GTETRGA_A	GTIOC5B_A		DRX0	RXD0_A/ MISO0_A/ SCL0_A/ SCK1_A	SCL1_B	MISOA_A	AN022		CMPIN0		TS26	KR00/ IRQ2
49	37	37	-	-	-		P500									AN013	DA1_B			TS27	
50	-	-	-	-	-		P501									AN012			AMP3+		
51	-	-	-	-	-		P502									AN011			AMP3-		
52	38	38	A6	25	25		P015									AN010	DA1_A	IVCMP1	AMP2+	TS28	IRQ7
53	39	39	A5	26	26		P014									AN009	DA0	IVREF1	AMP2-	TS29	
54	40	40	B5	27	27		P013									AN008		IVCMP0	AMP1+		
55	41	41	B4	28	28		P012									AN007		IVREF0	AMP1-		

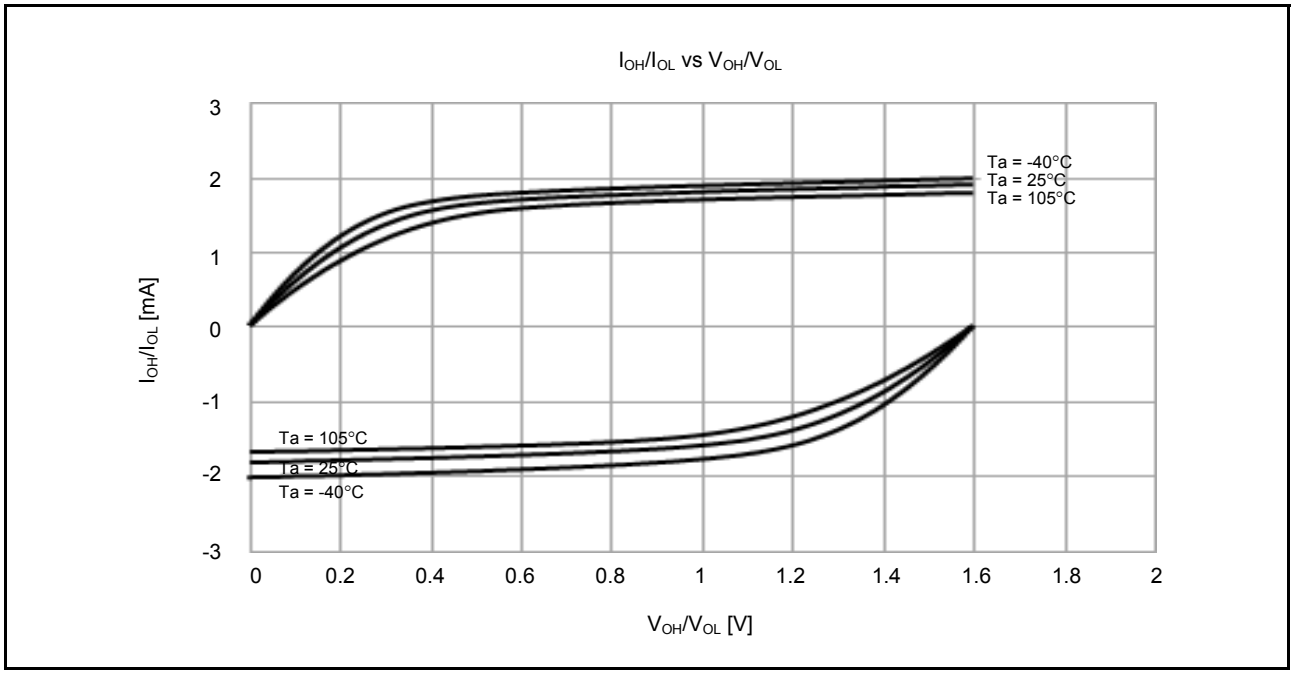


Figure 2.3 V_{OH}/V_{OL} and I_{OH}/I_{OL} temperature characteristics at VCC = 1.6 V when low drive output is selected (reference data, except for P914 and P915)

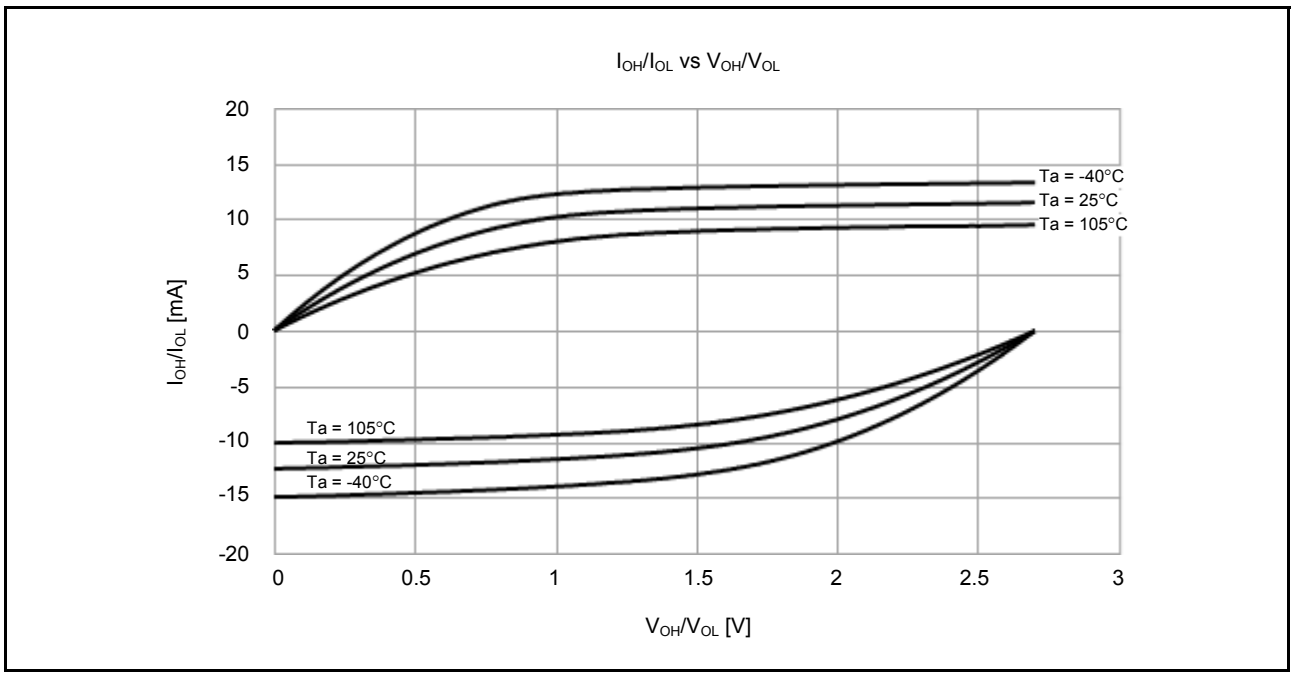


Figure 2.4 V_{OH}/V_{OL} and I_{OH}/I_{OL} temperature characteristics at VCC = 2.7 V when low drive output is selected (reference data, except for P914 and P915)

2.2.9 Operating and Standby Current

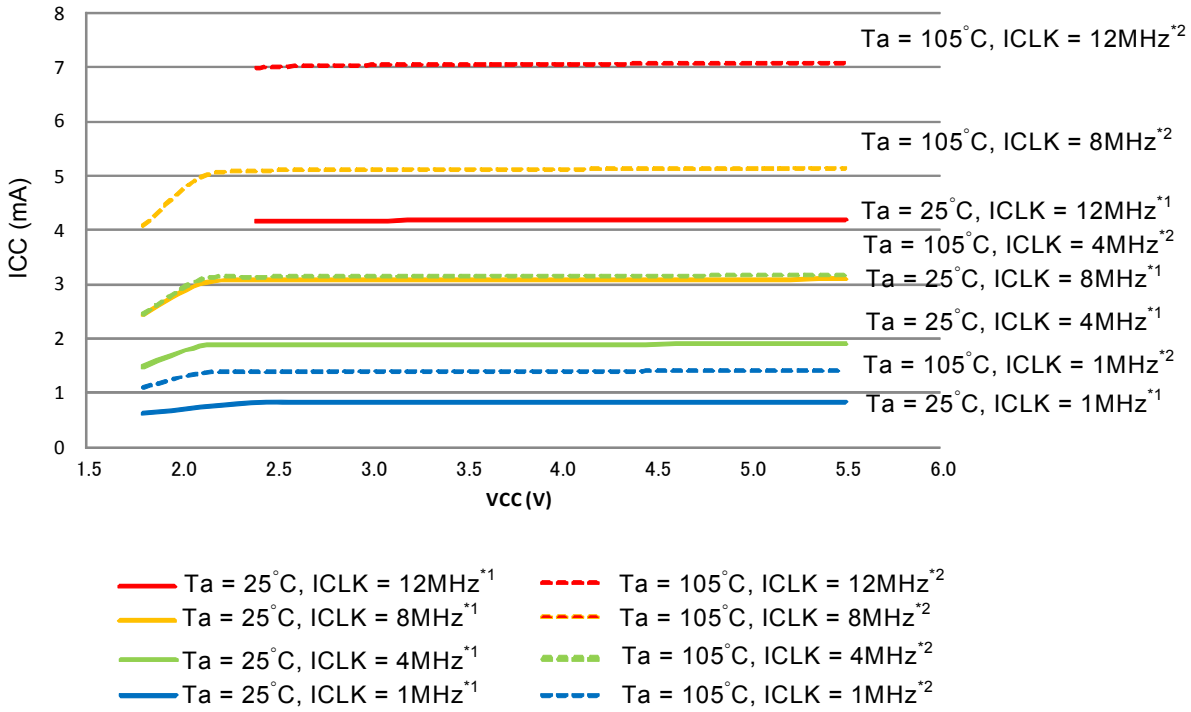
Table 2.11 Operating and standby current (1) (1 of 2)
Conditions: VCC = AVCC0 = 1.6 to 5.5 V

Parameter					Symbol	Typ*9	Max	Unit	Test Conditions
Supply current*1	High-speed mode*2	Normal mode	All peripheral clock disabled, while (1) code executing from flash*5	ICLK = 32 MHz	I_{CC}	4.2	-	mA	*7
				ICLK = 16 MHz		2.6	-		
				ICLK = 8 MHz		1.8	-		
			All peripheral clock disabled, CoreMark code executing from flash*5	ICLK = 32 MHz		6.2	-		
				ICLK = 16 MHz		3.6	-		
				ICLK = 8 MHz		2.4	-		
			All peripheral clock enabled, while (1) code executing from flash*5	ICLK = 32 MHz		10.5	-		*8
				ICLK = 16 MHz		5.8	-		
				ICLK = 8 MHz		3.4	-		
			All peripheral clock enabled, code executing from flash*5	ICLK = 32 MHz		-	22.1		
		Sleep mode	All peripheral clock disabled*5	ICLK = 32 MHz		1.6	-		*7
				ICLK = 16 MHz		1.2	-		
				ICLK = 8 MHz		0.9	-		
			All peripheral clock enabled*5	ICLK = 32 MHz		7.5	-		*8
				ICLK = 16 MHz		4.1	-		
				ICLK = 8 MHz		2.4	-		
		Increase during BGO operation*6				2.5	-		-
	Middle-speed mode*2	Normal mode	All peripheral clock disabled, while (1) code executing from flash*5	ICLK = 12 MHz	I_{CC}	1.9	-	mA	*7
				ICLK = 8 MHz		1.6	-		
			All peripheral clock disabled, CoreMark code executing from flash*5	ICLK = 12 MHz		2.7	-		
				ICLK = 8 MHz		2.1	-		
			All peripheral clock enabled, while (1) code executing from flash*5	ICLK = 12 MHz		4.3	-		*8
				ICLK = 8 MHz		3.1	-		
			All peripheral clock enabled, code executing from flash*5	ICLK = 12 MHz		-	8.1		
		Sleep mode	All peripheral clock disabled*5	ICLK = 12 MHz		0.8	-		*7
				ICLK = 8 MHz		0.8	-		
			All peripheral clock enabled*5	ICLK = 12 MHz		3.0	-		*8
				ICLK = 8 MHz		2.2	-		
		Increase during BGO operation*6				2.5	-		-
	Low-speed mode*3	Normal mode	All peripheral clock disabled, while (1) code executing from flash*5	ICLK = 1 MHz	I_{CC}	0.3	-	mA	*7
			All peripheral clock disabled, CoreMark code executing from flash*5	ICLK = 1 MHz		0.4	-		
			All peripheral clock enabled, while (1) code executing from flash*5	ICLK = 1 MHz		0.5	-		*8
			All peripheral clock enabled, code executing from flash*5	ICLK = 1 MHz		-	2.0		
		Sleep mode	All peripheral clock disabled*5	ICLK = 1 MHz		0.2	-		*7
			All peripheral clock enabled*5	ICLK = 1 MHz		0.4	-		*8

Table 2.11 Operating and standby current (1) (2 of 2)
Conditions: VCC = AVCC0 = 1.6 to 5.5 V

Parameter					Symbol	Typ*9	Max	Unit	Test Conditions
Supply current*1	Low-voltage mode*3	Normal mode	All peripheral clock disabled, while (1) code executing from flash*5	ICLK = 4 MHz	I_{CC}	1.5	-	mA	*7
			All peripheral clock disabled, CoreMark code executing from flash*5	ICLK = 4 MHz		1.4	-		
			All peripheral clock enabled, while (1) code executing from flash*5	ICLK = 4 MHz		2.3	-		*8
			All peripheral clock enabled, code executing from flash*5	ICLK = 4 MHz		-	4.0		
		Sleep mode	All peripheral clock disabled*5	ICLK = 4 MHz		0.9	-		*7
			All peripheral clock enabled*5	ICLK = 4 MHz		1.7	-		*8
	Subosc-speed mode*4	Normal mode	All peripheral clock disabled, while (1) code executing from flash*5	ICLK = 32.768 kHz	I_{CC}	5.9	-	µA	*7
			All peripheral clock enabled, while (1) code executing from flash*5	ICLK = 32.768 kHz		13.0	-		*8
			All peripheral clock enabled, code executing from flash*5	ICLK = 32.768 kHz		128.3 (17.8)*10	163.7		
		Sleep mode	All peripheral clock disabled*5	ICLK = 32.768 kHz		3.2	-		*7
			All peripheral clock enabled*5	ICLK = 32.768 kHz		10.0	-		*8

Note 1. Supply current values do not include output charge/discharge current from all pins. The values apply when internal pull-up MOSs are in the off state.
Note 2. The clock source is HOCO.
Note 3. The clock source is MOCO.
Note 4. The clock source is the sub-clock oscillator.
Note 5. This does not include BGO operation.
Note 6. This is the increase for programming or erasure of the ROM or flash memory for data storage during program execution.
Note 7. PCLKB and PCLKD are set to divided by 64.
Note 8. PCLKB and PCLKD are the same frequency as that of ICLK.
Note 9. VCC = 3.3 V.
Note 10. MOCO and DAC is stopped.



Note 1. All peripheral operations except any BGO operation are operating normally. This is the average of the actual measurements of the sample cores during product evaluation.

Note 2. All peripheral operations except any BGO operation are operating at maximum. This is the average of the actual measurements for the upper-limit samples during product evaluation.

Figure 2.18 Voltage dependency in middle-speed mode (reference data)

2.3.4 Wakeup Time

Table 2.23 Timing of recovery from low power modes (1)

Parameter				Symbol	Min	Typ	Max	Unit	Test conditions
Recovery time from Software Standby mode*1	High-speed mode	Crystal resonator connected to main clock oscillator	System clock source is main clock oscillator (20 MHz)*2	t_{SBYMC}	-	2	3	ms	Figure 2.31
		External clock input to main clock oscillator	System clock source is main clock oscillator (20 MHz)*3	t_{SBYEX}	-	14	25	µs	
		System clock source is HOCO*4 (HOCO clock is 32 MHz)		t_{SBYHO}	-	43	52	µs	
		System clock source is HOCO*4 (HOCO clock is 48 MHz)		t_{SBYHO}	-	44	52	µs	
		System clock source is HOCO*5 (HOCO clock is 64 MHz)		t_{SBYHO}	-	82	110	µs	
		System clock source is MOCO		t_{SBYMO}	-	16	25	µs	

Note 1. The division ratio of ICK and PCKx is the minimum division ratio within the allowable frequency range. The recovery time is determined by the system clock source.
Note 2. The Main Clock Oscillator Wait Control Register (MOSCWTCR) is set to 05h.
Note 3. The Main Clock Oscillator Wait Control Register (MOSCWTCR) is set to 00h.
Note 4. The HOCO clock wait control register (HOCOWTCR) is set to 05h.
Note 5. The HOCO clock wait control register (HOCOWTCR) is set to 06h.

Table 2.24 Timing of recovery from low power modes (2)

Parameter				Symbol	Min	Typ	Max	Unit	Test conditions
Recovery time from Software Standby mode*1	Middle-speed mode	Crystal resonator connected to main clock oscillator	System clock source is main clock oscillator (12 MHz)*2	t_{SBYMC}	-	2	3	ms	Figure 2.31
		External clock input to main clock oscillator	System clock source is main clock oscillator (12 MHz)*3	t_{SBYEX}	-	2.9	10	µs	
		System clock source is HOCO*4		t_{SBYHO}	-	38	50	µs	
		System clock source is MOCO (8 MHz)		t_{SBYMO}	-	3.5	5.5	µs	

Note 1. The division ratio of ICK and PCKx is the minimum division ratio within the allowable frequency range. The recovery time is determined by the system clock source.
Note 2. The Main Clock Oscillator Wait Control Register (MOSCWTCR) is set to 05h.
Note 3. The Main Clock Oscillator Wait Control Register (MOSCWTCR) is set to 00h.
Note 4. The system clock is 12 MHz.

Table 2.34 SCI timing (2)
Conditions: VCC = AVCC0 = 1.6 to 5.5 V

Parameter				Symbol	Min	Max	Unit*1	Test conditions
Simple SPI	SCK clock cycle output (master)			t_{SPcyc}	4	65536	t_{Pcyc}	Figure 2.43
	SCK clock cycle input (slave)				6	65536		
	SCK clock high pulse width			t_{SPCKWH}	0.4	0.6	t_{SPcyc}	
	SCK clock low pulse width			t_{SPCKWL}	0.4	0.6	t_{SPcyc}	
	SCK clock rise and fall time		1.8V or above	t_{SPCKr}, t_{SPCKf}	-	20	ns	
			1.6V or above		-	30		
	Data input setup time	Master	2.7V or above	t_{SU}	45	-	ns	Figure 2.44 to Figure 2.47
			2.4V or above		55	-		
			1.8V or above		80	-		
			1.6V or above		110	-		
		Slave	2.7V or above		40	-		
			1.6V or above		45	-		
	Data input hold time	Master		t_H	33.3	-	ns	
		Slave			40	-		
	SS input setup time			t_{LEAD}	1	-	t_{SPcyc}	
	SS input hold time			t_{LAG}	1	-	t_{SPcyc}	
	Data output delay	Master	1.8V or above	t_{OD}	-	40	ns	
			1.6V or above		-	50		
		Slave	2.4V or above		-	65		
			1.8V or above		-	100		
			1.6V or above		-	125		
	Data output hold time	Master	2.7V or above	t_{OH}	–10	-	ns	
			2.4V or above		–20	-		
			1.8V or above		–30	-		
			1.6V or above		–40	-		
		Slave			–10	-		
	Data rise and fall time	Master		t_{Dr}, t_{Df}	-	20	ns	
		Slave	1.8V or above		-	20		
			1.6V or above		-	30		
Simple SPI	Slave access time			t_{SA}	-	6	t_{Pcyc}	Figure 2.47
	Slave output release time			t_{REL}	-	6	t_{Pcyc}	

Note 1. t_{Pcyc}: PCLKB cycle.

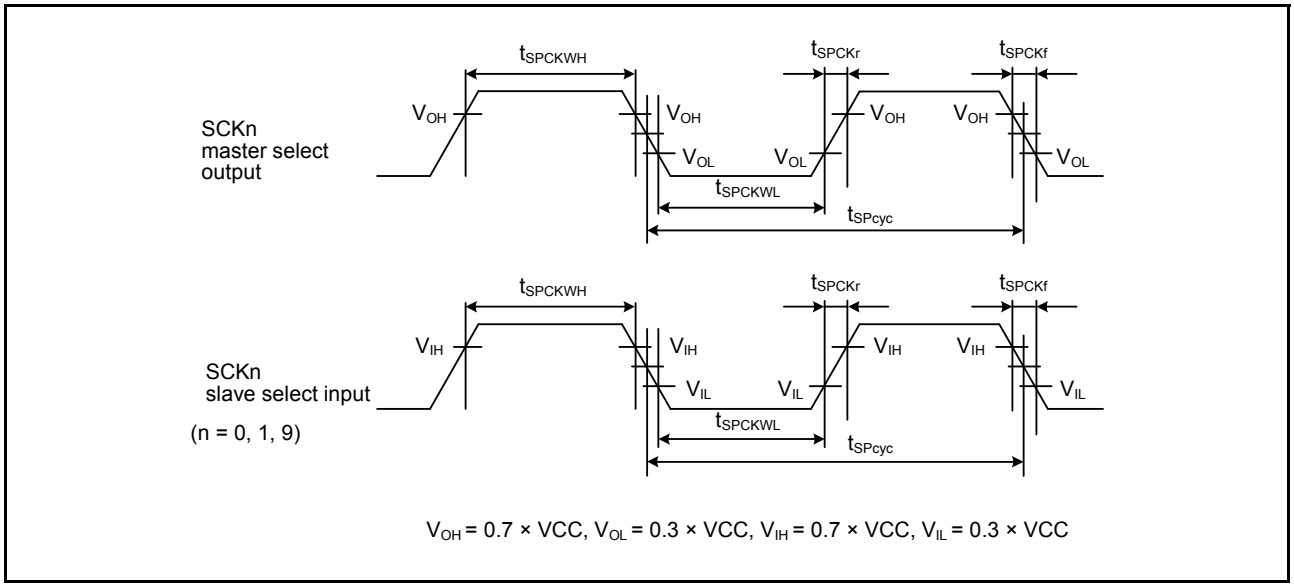


Figure 2.43 SCI simple SPI mode clock timing

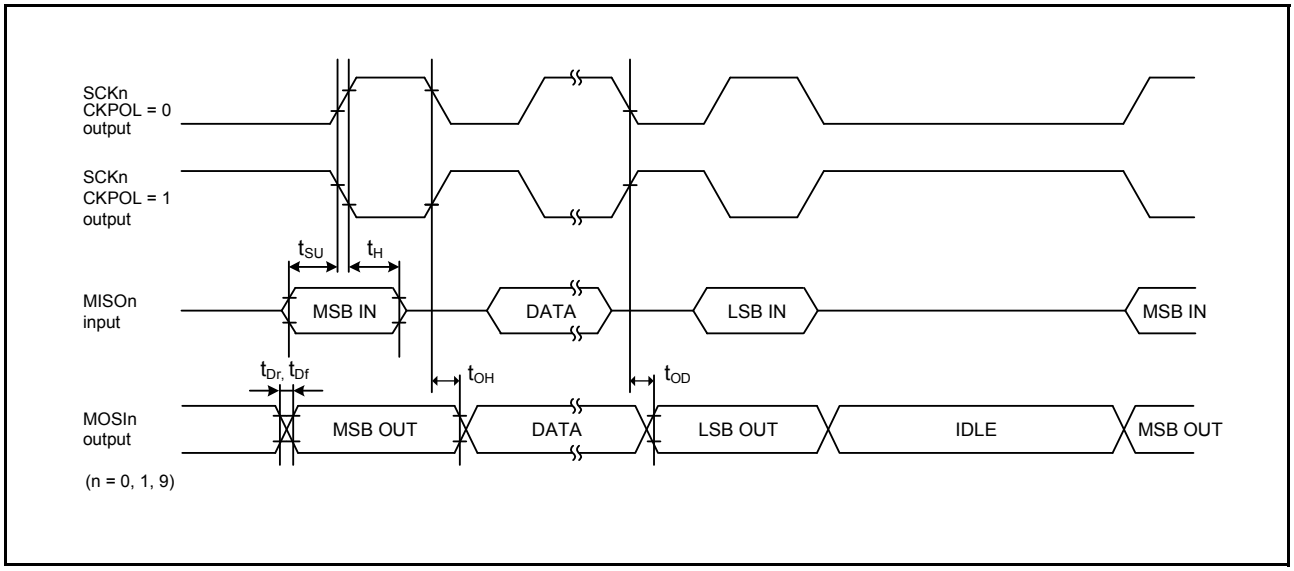


Figure 2.44 SCI simple SPI mode timing (master, CKPH = 1)

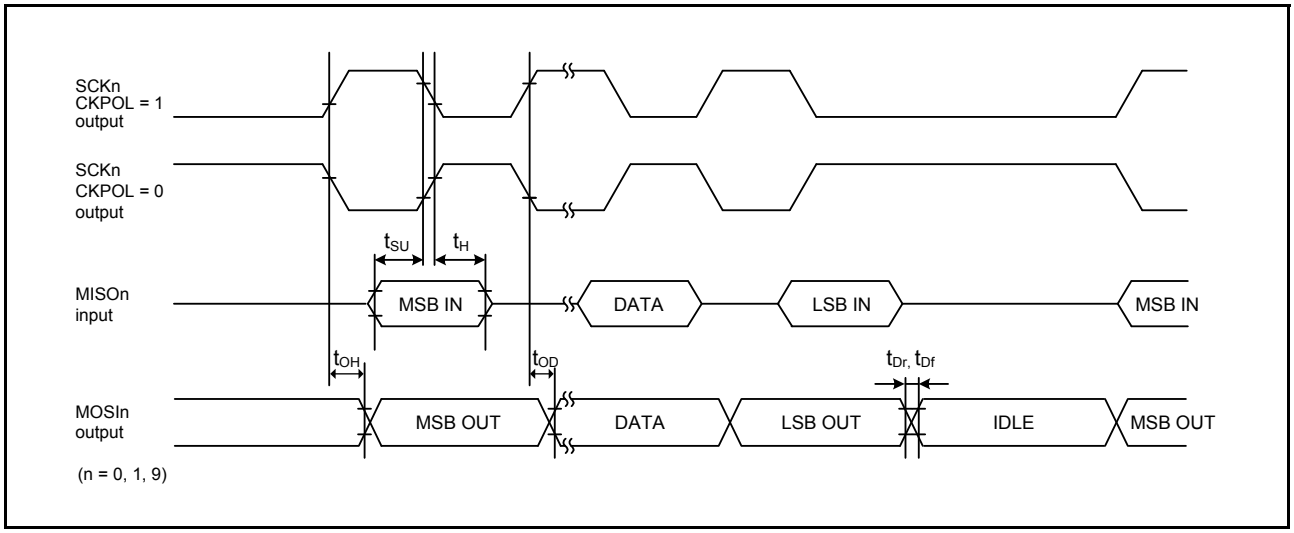


Figure 2.45 SCI simple SPI mode timing (master, CKPH = 0)

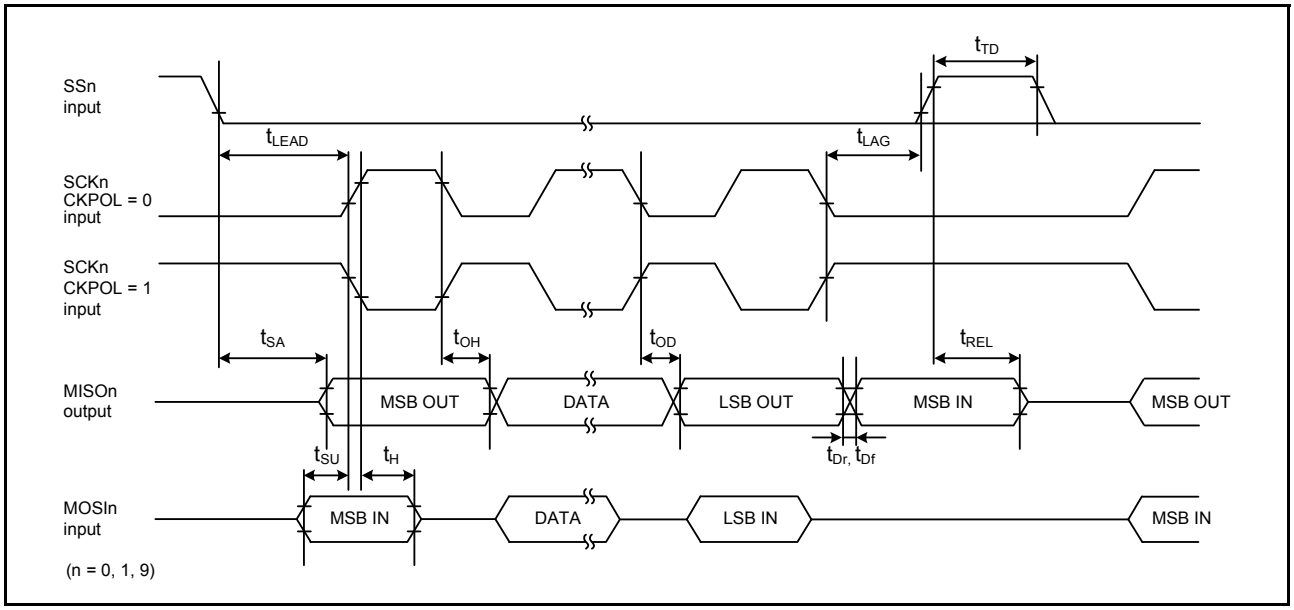


Figure 2.46 SCI simple SPI mode timing (slave, CKPH = 1)

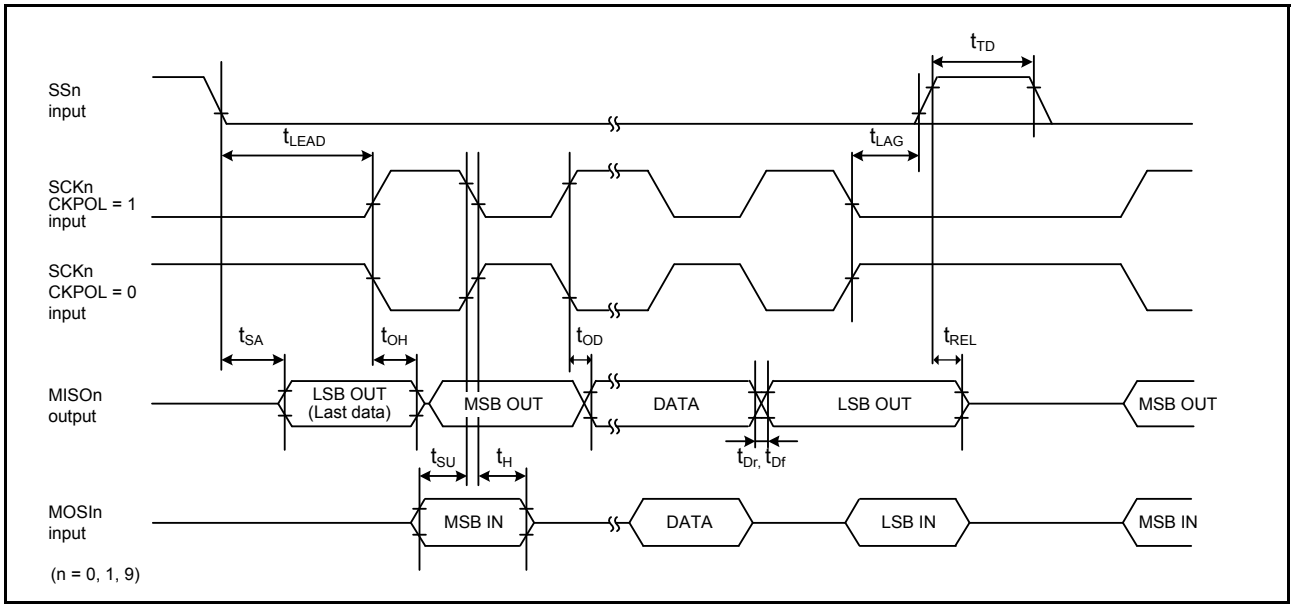


Figure 2.47 SCI simple SPI mode timing (slave, CKPH = 0)

Table 2.35 SCI timing (3)

Conditions: VCC = AVCC0 = 2.7 to 5.5 V

Parameter		Symbol	Min	Max	Unit	Test conditions
Simple IIC (Standard mode)	SDA input rise time	t_{Sr}	-	1000	ns	Figure 2.48
	SDA input fall time	t_{Sf}	-	300	ns	
	SDA input spike pulse removal time	t_{SP}	0	4 × t_{IICcyc}	ns	
	Data input setup time	t_{SDAS}	250	-	ns	
	Data input hold time	t_{SDAH}	0	-	ns	
	SCL, SDA capacitive load	C_b*1	-	400	pF	
Simple IIC (Fast mode)	SDA input rise time	t_{Sr}	-	300	ns	Figure 2.48
	SDA input fall time	t_{Sf}	-	300	ns	
	SDA input spike pulse removal time	t_{SP}	0	4 × t_{IICcyc}	ns	
	Data input setup time	t_{SDAS}	100	-	ns	
	Data input hold time	t_{SDAH}	0	-	ns	
	SCL, SDA capacitive load	C_b*1	-	400	pF	

Note: t_{IICcyc}: IIC internal reference clock (IICφ) cycle.

Note 1. Cb indicates the total capacity of the bus line.

Table 2.36 SPI timing (2 of 2)

Conditions: Middle drive output is selected in the Port Drive Capability bit in the PmnPFS register.

Parameter				Symbol	Min	Max	Unit*1	Test conditions
SPI	Data input setup time	Master		t_{SU}	10	-	ns	Figure 2.50 to Figure 2.55 C = 30pF
		Slave	2.4V or above		10	-		
			1.8V or above		15	-		
			1.6V or above		20	-		
	Data input hold time	Master (RSPCK is PCLKB/2)		t_{HF}	0	-	ns	
		Master (RSPCK is not PCLKB/2)		t_{H}	t_{Pcyc}	-		
		Slave		t_{H}	20	-		
	SSL setup time	Master		t_{LEAD}	– 30 + N x t_{Spcyc}*2	-	ns	
		Slave			6 x t_{Pcyc}	-	ns	
	SSL hold time	Master		t_{LAG}	– 30 + N x t_{Spcyc}*3	-	ns	
		Slave			6 x t_{Pcyc}	-	ns	
	Data output delay	Master	2.7V or above	t_{OD}	-	14	ns	Figure 2.50 to Figure 2.55 C = 30pF
			2.4V or above		-	20		
			1.8V or above		-	25		
			1.6V or above		-	30		
		Slave	2.7V or above		-	50		
			2.4V or above		-	60		
			1.8V or above		-	85		
			1.6V or above		-	110		
	Data output hold time	Master		t_{OH}	0	-	ns	
		Slave			0	-		
	Successive transmission delay	Master		t_{TD}	t_{SPcyc} + 2 × t_{Pcyc}	8 × t_{SPcyc} + 2 × t_{Pcyc}	ns	
		Slave			6 × t_{Pcyc}	-		
	MOSI and MISO rise and fall time	Output	2.7V or above	t_{Dr}, t_{Df}	-	10	ns	
			2.4V or above		-	15		
			1.8V or above		-	20		
			1.6V or above		-	30		
		Input			-	1	µs	
	SSL rise and fall time	Output	2.7V or above	t_{SSLr}, t_{SSLf}	-	10	ns	
			2.4V or above		-	15		
			1.8V or above		-	20		
			1.6V or above		-	30		
		Input			-	1	µs	
	Slave access time		2.4V or above	t_{SA}	-	2 × t_{Pcyc} +100	ns	Figure 2.54 and Figure 2.55 C = 30pF
			1.8V or above		-	2 × t_{Pcyc} +140		
			1.6V or above		-	2 × t_{Pcyc} +180		
	Slave output release time		2.4V or above	t_{REL}	-	2 × t_{Pcyc} +100	ns	
			1.8V or above		-	2 × t_{Pcyc} +140		
			1.6V or above		-	2 × t_{Pcyc} +180		

Note 1. t_{Pcyc}: PCLKB cycle.
Note 2. N is set as an integer from 1 to 8 by the SPCKD register.
Note 3. N is set as an integer from 1 to 8 by the SSLND register.

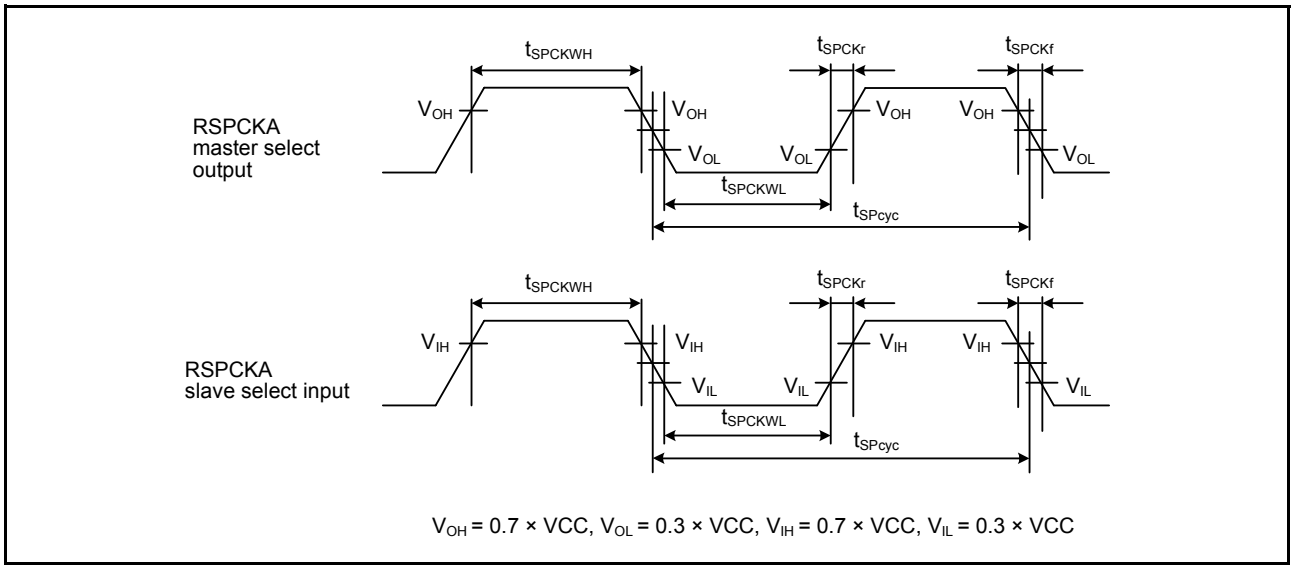


Figure 2.49 SPI clock timing

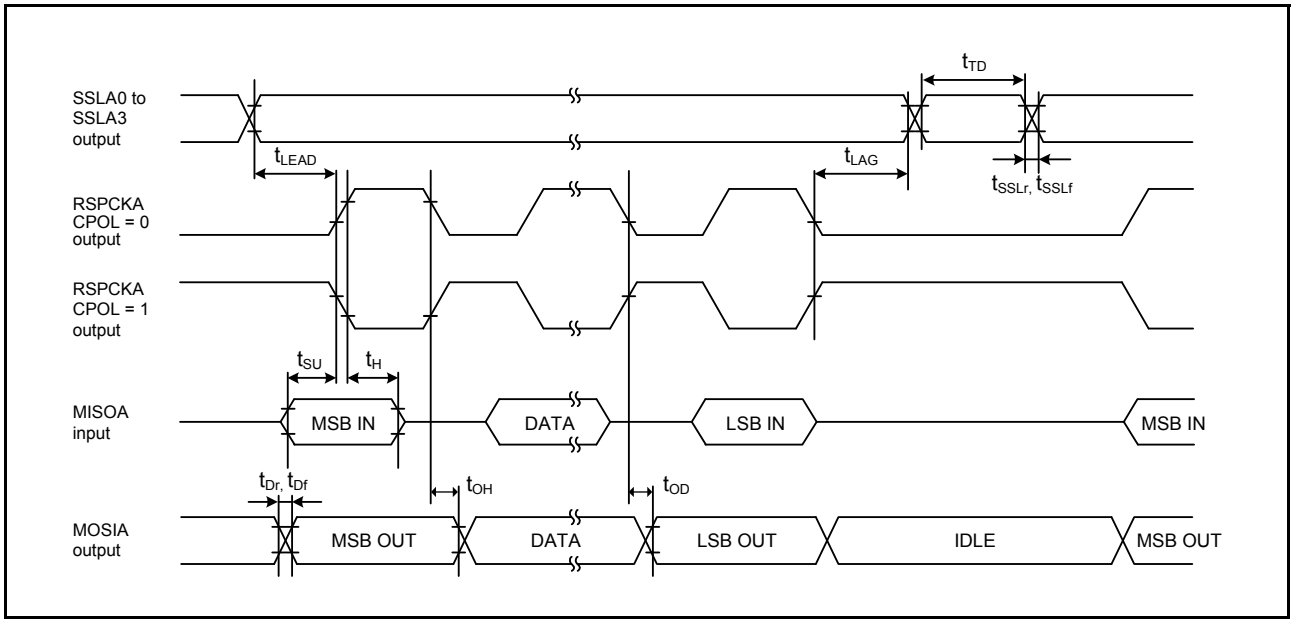


Figure 2.50 SPI timing (master, CPHA = 0) (bit rate: PCLKB division ratio is set to any value other than 1/2)

2.3.11 IIC Timing

Table 2.37 IIC timing
Conditions: VCC = AVCC0 = 2.7 to 5.5 V

Parameter		Symbol	Min*1	Max	Unit	Test conditions
IIC (standard mode, SMBus)	SCL input cycle time	t_{SCL}	6 (12) × t_{IICcyc} + 1300	-	ns	Figure 2.56
	SCL input high pulse width	t_{SCLH}	3 (6) × t_{IICcyc} + 300	-	ns	
	SCL input low pulse width	t_{SCLL}	3 (6) × t_{IICcyc} + 300	-	ns	
	SCL, SDA input rise time	t_{Sr}	-	1000	ns	
	SCL, SDA input fall time	t_{Sf}	-	300	ns	
	SCL, SDA input spike pulse removal time	t_{SP}	0	1 (4) × t_{IICcyc}	ns	
	SDA input bus free time (When wakeup function is disabled)	t_{BUF}	3 (6) × t_{IICcyc} + 300	-	ns	
	SDA input bus free time (When wakeup function is enabled)	t_{BUF}	3 (6) × t_{IICcyc} + 4 × t_{Pcyc} + 300	-	ns	
	START condition input hold time (When wakeup function is disabled)	t_{STAH}	t_{IICcyc} + 300	-	ns	
	START condition input hold time (When wakeup function is enabled)	t_{STAH}	1 (5) × t_{IICcyc} + t_{Pcyc} + 300	-	ns	
	Repeated START condition input setup time	t_{STAS}	1000	-	ns	
	STOP condition input setup time	t_{STOS}	1000	-	ns	
	Data input setup time	t_{SDAS}	t_{IICcyc} + 50	-	ns	
	Data input hold time	t_{SDAH}	0	-	ns	
	SCL, SDA capacitive load	C_b	-	400	pF	
IIC (Fast mode)	SCL input cycle time	t_{SCL}	6 (12) × t_{IICcyc} + 600	-	ns	Figure 2.56
	SCL input high pulse width	t_{SCLH}	3 (6) × t_{IICcyc} + 300	-	ns	
	SCL input low pulse width	t_{SCLL}	3 (6) × t_{IICcyc} + 300	-	ns	
	SCL, SDA input rise time	t_{Sr}	-	300	ns	
	SCL, SDA input fall time	t_{Sf}	-	300	ns	
	SCL, SDA input spike pulse removal time	t_{SP}	0	1 (4) × t_{IICcyc}	ns	
	SDA input bus free time (When wakeup function is disabled)	t_{BUF}	3 (6) × t_{IICcyc} + 300	-	ns	
	SDA input bus free time (When wakeup function is enabled)	t_{BUF}	3 (6) × t_{IICcyc} + 4 × t_{Pcyc} + 300	-	ns	
	START condition input hold time (When wakeup function is disabled)	t_{STAH}	t_{IICcyc} + 300	-	ns	
	START condition input hold time (When wakeup function is enabled)	t_{STAH}	1(5) × t_{IICcyc} + t_{Pcyc} + 300	-	ns	
	Repeated START condition input setup time	t_{STAS}	300	-	ns	
	STOP condition input setup time	t_{STOS}	300	-	ns	
	Data input setup time	t_{SDAS}	t_{IICcyc} + 50	-	ns	
	Data input hold time	t_{SDAH}	0	-	ns	
	SCL, SDA capacitive load	C_b	-	400	pF	

Note: t_{IICcyc}: IIC internal reference clock (IICφ) cycle, t_{Pcyc}: PCLKB cycle

Note 1. Values in parentheses apply when ICMR3.NF[1:0] is set to 11b while the digital filter is enabled with ICFER.NFE set to 1.

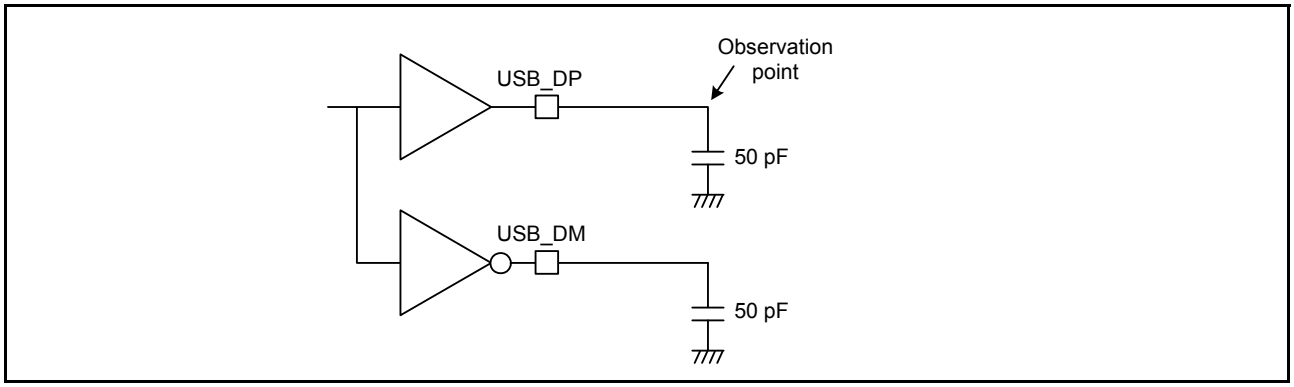


Figure 2.59 Test circuit for Full-Speed (FS) connection

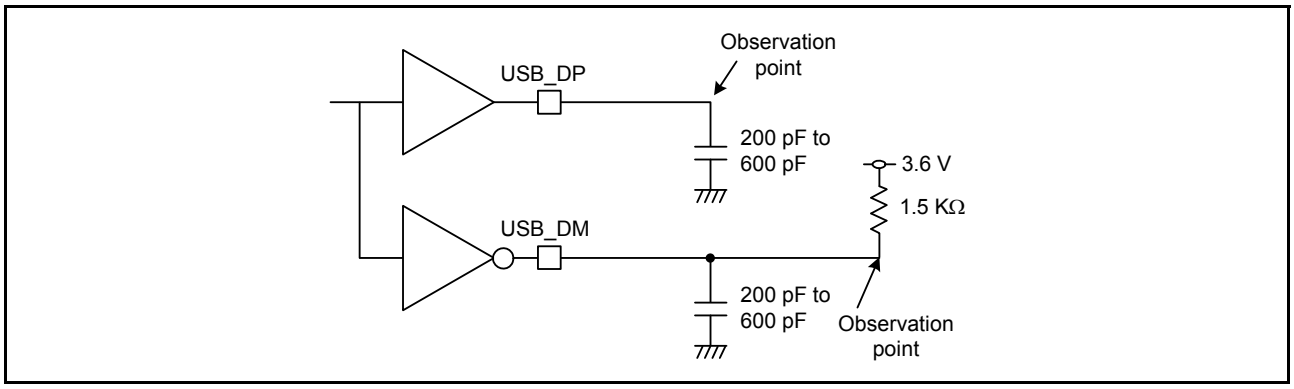


Figure 2.60 Test circuit for Low-Speed (LS) connection

2.4.2 USB External Supply

Table 2.40 USB regulator

Parameter		Min	Typ	Max	Unit	Test conditions
VCC_USB supply current	VCC_USB_LDO ≥ 3.8V	-	-	50	mA	-
	VCC_USB_LDO ≥ 4.5V	-	-	100	mA	-
VCC_USB supply voltage		3.0	-	3.6	V	-

2.6 DAC8 Characteristics

Table 2.50 D/A conversion characteristics
Conditions: VCC = AVCC0 = 1.8 to 5.5 V

Parameter		Min	Typ	Max	Unit	Test conditions
Resolution		-	-	8	bit	-
Charge pump stabilization time		-	-	100	µs	-
Conversion time	VCC = 2.7 to 5.5V	-	-	3.0	µs	35-pF capacitive load
	VCC = 1.8 to 2.7V	-	-	6.0	µs	
Absolute accuracy	VCC = 2.4 to 5.5V	-	-	±3.0	LSB	2-MΩ resistive load
	VCC = 1.8 to 2.4V	-	-	±3.5		
	VCC = 2.4 to 5.5V	-	-	±2.0	LSB	4-MΩ resistive load
	VCC = 1.8 to 2.4V	-	-	±2.5		
RO output resistance		-	6.4	-	kΩ	-

2.7 TSN Characteristics

Table 2.51 TSN characteristics
Conditions: VCC = AVCC0 = 2.0 to 5.5 V

Parameter	Symbol	Min	Typ	Max	Unit	Test conditions
Relative accuracy	-	-	±1.5	-	°C	2.4 V or above
		-	±2.0	-	°C	Below 2.4 V
Temperature slope	-	-	–3.65	-	mV/°C	-
Output voltage (at 25°C)	-	-	1.05	-	V	VCC = 3.3 V
Temperature sensor start time	t_{START}	-	-	5	µs	-
Sampling time	-	5	-	-	µs	

2.8 OSC Stop Detect Characteristics

Table 2.52 Oscillation stop detection circuit characteristics

Parameter	Symbol	Min	Typ	Max	Unit	Test conditions
Detection time	t_{dr}	-	-	1	ms	Figure 2.63

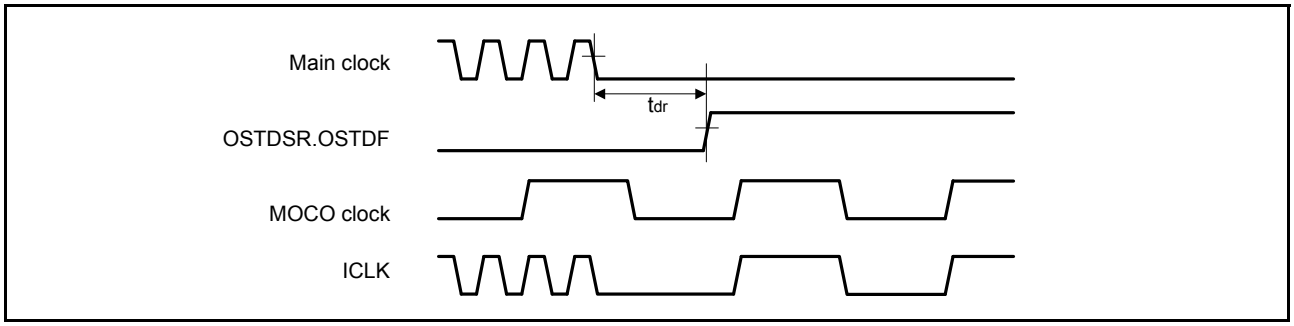


Figure 2.63 Oscillation stop detection timing

Table 2.54 Power-on reset circuit and voltage detection circuit characteristics (2) (2 of 2)

Parameter	Symbol	Min	Typ	Max	Unit	Test Conditions
Power-on reset enable time	$t_{W\ (POR)}$	1	-	-	ms	Figure 2.65, VCC = below 1.0 V
LVD operation stabilization time (after LVD is enabled)	$T_{d\ (E-A)}$	-	-	300	µs	Figure 2.67, Figure 2.68
Hysteresis width (POR)	V_{PORH}	-	110	-	mV	-
Hysteresis width (LVD0, LVD1 and LVD2)	V_{LVH}	-	60	-	mV	LVD0 selected
		-	100	-		V_{det1_0} to V_{det1_2} selected.
		-	60	-		V_{det1_3} to V_{det1_9} selected.
		-	50	-		V_{det1_A} to V_{det1_B} selected.
		-	40	-		V_{det1_C} to V_{det1_F} selected.
		-	60	-		LVD2 selected

Note 1. When OFS1.LVDAS = 0
Note 2. When OFS1.LVDAS = 1
Note 3. The minimum VCC down time indicates the time when VCC is below the minimum value of voltage detection levels V_{POR}, V_{det0}, V_{det1}, and V_{det2} for the POR/LVD.

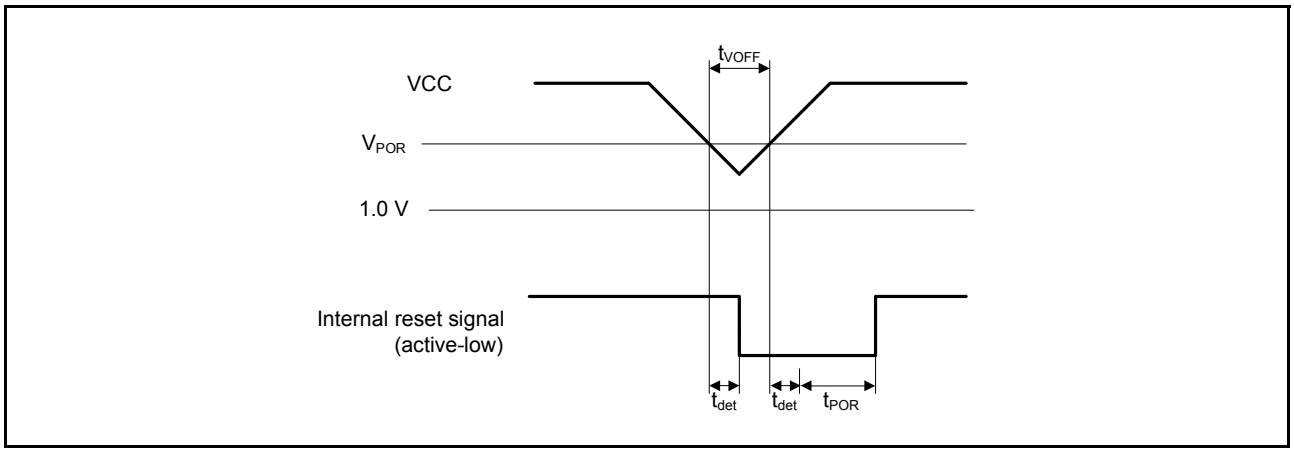
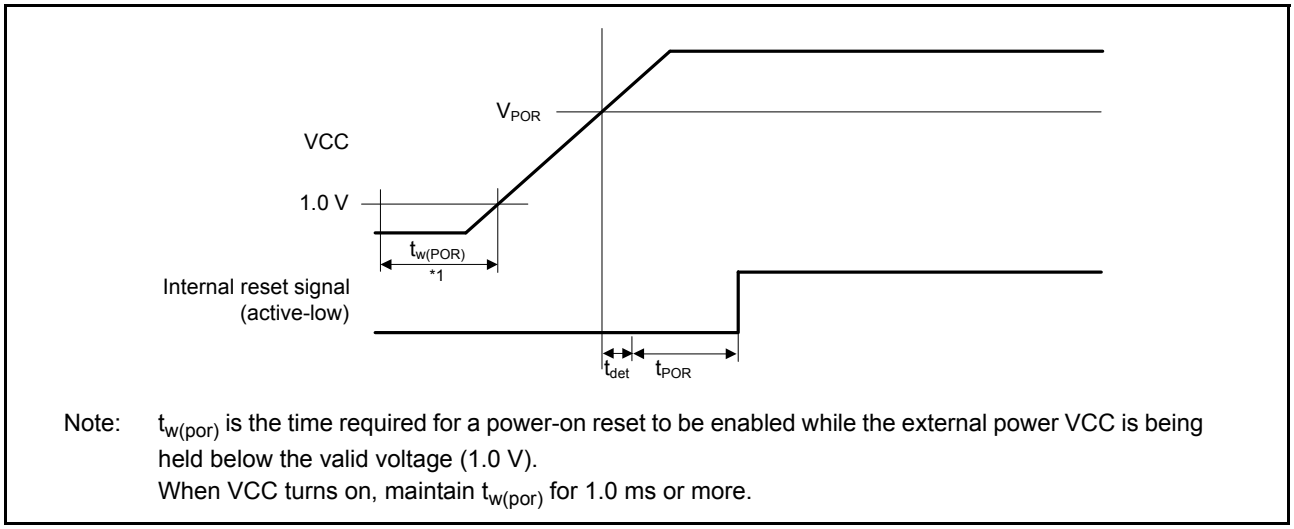


Figure 2.64 Voltage detection reset timing



Note: $t_{w(por)}$ is the time required for a power-on reset to be enabled while the external power VCC is being held below the valid voltage (1.0 V).
When VCC turns on, maintain $t_{w(por)}$ for 1.0 ms or more.

Figure 2.65 Power-on reset timing

Table 2.61 Code flash characteristics (3)

Middle-speed operating mode
Conditions: VCC = AVCC0 = 1.8 to 5.5 V, Ta = –40 to +85°C

Parameter		Symbol	ICLK = 1 MHz			ICLK = 8 MHz			Unit
			Min	Typ	Max	Min	Typ	Max	
Programming time	4 bytes	t_{P4}	-	157	1411	-	101	966	µs
Erasure time	1 KB	t_{E1K}	-	9.10	289	-	6.10	228	ms
Blank check time	2 bytes	t_{BC4}	-	-	87.7	-	-	52.5	µs
	1 KB	t_{BC1K}	-	-	1930	-	-	414	µs
Erase suspended time		t_{SED}	-	-	32.7	-	-	21.6	µs
Startup area switching setting time		t_{SAS}	-	22.8	592	-	14.2	465	ms
Access window time		t_{AWS}	-	22.8	592	-	14.2	465	ms
OCD/serial programmer ID setting time		t_{OSIS}	-	22.8	592	-	14.2	465	ms
Flash memory mode transition wait time 1		t_{DIS}	2	-	-	2	-	-	µs
Flash memory mode transition wait time 2		t_{MS}	720	-	-	720	-	-	ns

Note 1. Does not include the time until each operation of the flash memory is started after instructions are executed by the software.
Note 2. The lower-limit frequency of ICLK is 1 MHz during programming or erasing the flash memory. When using ICLK at below 4 MHz, the frequency can be set to 1 MHz, 2 MHz, or 3 MHz. A non-integer frequency such as 1.5 MHz cannot be set.
Note 3. The frequency accuracy of ICLK must be ±3.5% during programming or erasing the flash memory. Confirm the frequency accuracy of the clock source.

2.13.2 Data Flash Memory Characteristics

Table 2.62 Data flash characteristics (1)

Parameter		Symbol	Min	Typ	Max	Unit	Conditions
Reprogramming/erasure cycle*1		N_{DPEC}	100000	1000000	-	Times	-
Data hold time	After 10000 times of N_{DPEC}	t_{DDRP}	20*2, *3	-	-	Year	Ta = +85°C
	After 100000 times of N_{DPEC}		5*2, *3	-	-	Year	
	After 1000000 times of N_{DPEC}		-	1*2, *3	-	Year	Ta = +25°C

Note 1. The reprogram/erase cycle is the number of erasure for each block. When the reprogram/erase cycle is n times (n = 100,000), erasing can be performed n times for each block. For instance, when 1-byte programming is performed 1,000 times for different addresses in 1-byte blocks, and then the entire block is erased, the reprogram/erase cycle is counted as one. However, programming the same address for several times as one erasure is not enabled. (overwriting is prohibited.)
Note 2. Characteristics when using the flash memory programmer and the self-programming library provided by Renesas Electronics.
Note 3. These results are obtained from reliability testing.

Renesas Synergy™ Platform
S128 Microcontroller

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R01DS0309EU0100